

APPLICATION DATA SHEET 35 U 28 APR 2006

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Application Information:

Title of Invention:	Method And Device For Reflow Soldering With Volume Flow Control
Application Type:	regular, utility
Attorney Docket Number:	2380.0030000

Botanic Information:

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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Domestic Priority Information:

This is a National Stage of US application number PCT/EP2004/012262, filed 2004-10-29, now pending.

Foreign Priority Information:

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